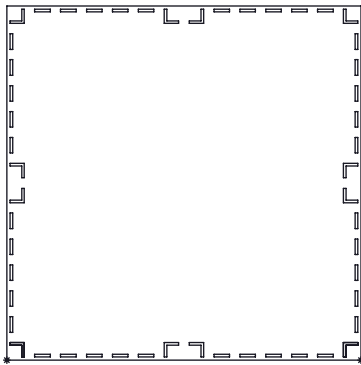
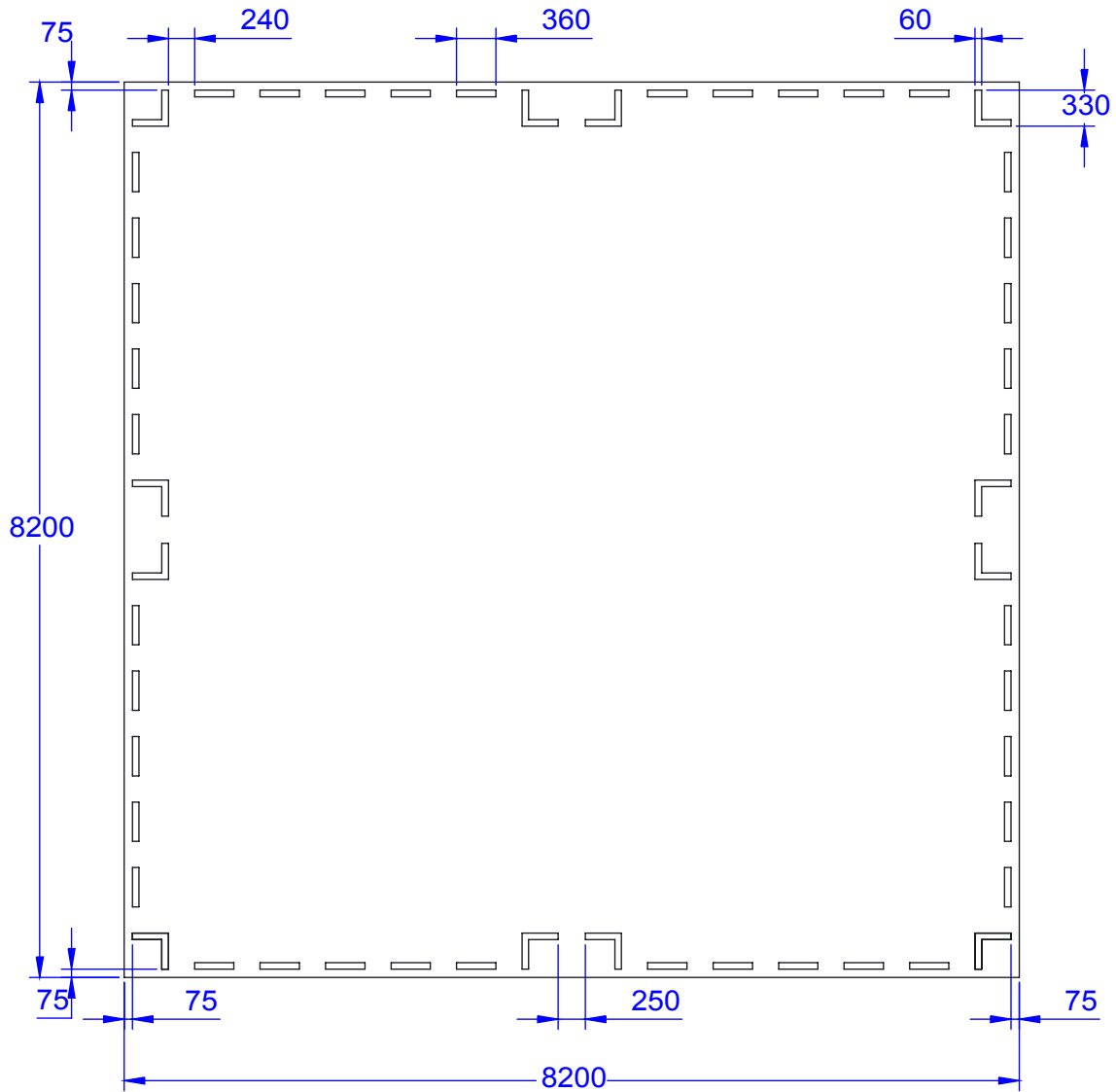


Notes: (Unless Otherwise Specified).

1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250um ~ 725um.
3. METALLIZATION 1.0 um ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

TopLine[®]			
TITLE DAISY CHAIN TEST DIE TD64 8X8MM			
SCALE	SIZE	DRAWING NO.	REV
	A	154064	A
DO NOT SCALE DRAWING			SHEET 1 OF 2

PERIMETER PAD TEST DIE
DAISY CHAIN



SCALE 1:175

DIMENSIONS IN MICRONS
1.0mm = 1000um

- Notes: (Unless Otherwise Specified).
1. DIE MATERIAL IS SILICON.
 2. DIE THICKNESS 250um ~ 725um.
 3. METALLIZATION 1.0 um ALUMINUM (Al).
 4. DIE IS WITHOUT PASSIVATION.
 5. WIRE BONDABLE WITH GOLD (Au) WIRE.
 6. DAISY CHAIN PAIRS.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	11/21/21				
ENG M. Hart	11/21/21	TITLE DAISY CHAIN TEST DIE			
MFG		TD64 8X8MM			
QA		SCALE	SIZE	DRAWING NO.	REV
CUST			A	154064	A
REVISED		DO NOT SCALE DRAWING			SHEET 2 OF 2